Title: URIC ACID ADDITIVE FOR CLEANING FORMULATIONS

Abstract: Compositions useful in microelectronic device manufacturing for cleaning of wafer substrates such as microelectronic device precursor structures. The compositions can be employed for processing of wafers that include copper metallization, for example, in operations such as post-chemical mechanical polishing cleaning of microelectronic device wafers. The aqueous compositions include at least one alkanolamine, at least one quaternary ammonium hydroxide, uric acid, at least one alcohol and at least one additional organic acid antioxidant.
INTERNATIONAL SEARCH REPORT

A. CLASSIFICATION OF SUBJECT MATTER
IPC: G03F 7/42(2006.01)

USPC: 510/175
According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED
Minimum documentation searched (classification system followed by classification symbols)
U.S. : 510/175

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched
None

Electronic data base consulted during the international search (name of data base and, where practicable, search terms used)
DERWENT

C. DOCUMENTS CONSIDERED TO BE RELEVANT

<table>
<thead>
<tr>
<th>Category</th>
<th>Citation of document, with indication, where appropriate, of the relevant passages</th>
<th>Relevant to claim No.</th>
</tr>
</thead>
<tbody>
<tr>
<td>A</td>
<td>US 6,440,326 A (MARUYAMA et al) 27 August 2002 (27.08.2002), abstract.</td>
<td>1</td>
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</tbody>
</table>

Further documents are listed in the continuation of Box C

See patent family annex

Date of the actual completion of the international search
17 July 2008 (17.07.2008)

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